# **NCE Automotive N-Channel Super Trench Power MOSFET**

### **Description**

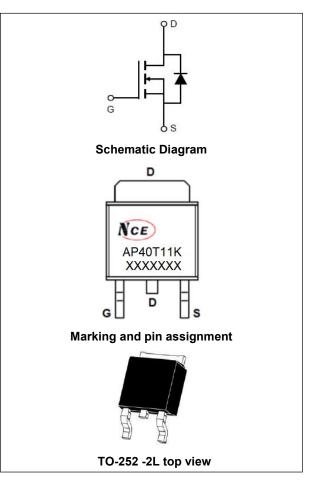
The NCEAP40T11K uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

#### **General Features**

- $V_{DS}$  =40V, $I_D$  =150A (Silicon Limited)  $R_{DS(ON)}$ =2.4m $\Omega$  (typical) @  $V_{GS}$ =10V  $R_{DS(ON)}$ =3.3m $\Omega$  (typical) @  $V_{GS}$ =4.5V
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested
- 100% ∆Vds tested
- AEC-Q101 qualified

### **Application**

- Automotive application
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



**Package Marking and Ordering Information** 

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AP40T11K	NCEAP40T11K	TO-252-2L	-	-	-

### Absolute Maximum Ratings (T<sub>c</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	40	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous (Silicon Limited) (Note1)	I <sub>D</sub>	150	Α
Drain Current-Continuous (Silicon Limited) (Note1)	I <sub>D</sub> (100°C)	107	А
Drain Current-Continuous (Package Limited)	I <sub>D</sub>	110	Α
Pulsed Drain Current	I <sub>DM</sub>	440	А
Maximum Power Dissipation	P <sub>D</sub>	150	W
Derating factor		1	W/°C
Single pulse avalanche energy (Note 2)	E <sub>AS</sub>	500	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	$^{\circ}$ C

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case	ReJC 1.0	°C/W
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# NCEAP40T11K

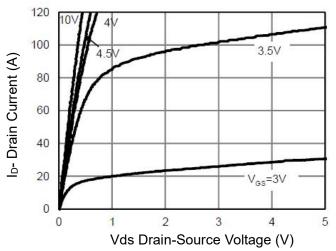
### Electrical Characteristics (Tc=25°C unless otherwise noted)

Off Characteristics  Drain-Source Breakdown Voltage  Zero Gate Voltage Drain Current  Gate-Body Leakage Current  On Characteristics  Gate Threshold Voltage  Drain-Source On-State Resistance	BVpss Ipss Igss Vgs(th) Rps(on) gfs	V <sub>GS</sub> =0V I <sub>D</sub> =250μA V <sub>DS</sub> =40V,V <sub>GS</sub> =0V V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA V <sub>GS</sub> =10V, I <sub>D</sub> =20A V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A V <sub>DS</sub> =5V,I <sub>D</sub> =20A	1.2	- - - 1.7 2.4 3.3 60	- 1 ±100 2.2 3.5 4.8	V μA nA V mΩ
Zero Gate Voltage Drain Current Gate-Body Leakage Current On Characteristics Gate Threshold Voltage	IDSS IGSS  VGS(th)  RDS(ON)  GFS	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA V <sub>GS</sub> =10V, I <sub>D</sub> =20A V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	1.2	1.7 2.4 3.3	1 ±100 2.2 3.5 4.8	μΑ nA V mΩ
Gate-Body Leakage Current  On Characteristics  Gate Threshold Voltage	IGSS  VGS(th)  RDS(ON)  GFS	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA V <sub>GS</sub> =10V, I <sub>D</sub> =20A V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	1.2	1.7 2.4 3.3	±100 2.2 3.5 4.8	nA V mΩ
On Characteristics Gate Threshold Voltage	V <sub>GS(th)</sub> R <sub>DS(ON)</sub> g <sub>FS</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA V <sub>GS</sub> =10V, I <sub>D</sub> =20A V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	1.2	1.7 2.4 3.3	2.2 3.5 4.8	V mΩ mΩ
Gate Threshold Voltage	R <sub>DS(ON)</sub> -	V <sub>GS</sub> =10V, I <sub>D</sub> =20A V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	2.4	3.5 4.8	mΩ mΩ
	R <sub>DS(ON)</sub> -	V <sub>GS</sub> =10V, I <sub>D</sub> =20A V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	2.4	3.5 4.8	mΩ mΩ
Drain-Source On-State Resistance	<b>G</b> FS	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A		3.3	4.8	mΩ
Drain-Source On-State Resistance	<b>G</b> FS					
		V <sub>DS</sub> =5V,I <sub>D</sub> =20A	-	60	_	
Forward Transconductance			· ·	1	_	S
Dynamic Characteristics						
Input Capacitance	C <sub>lss</sub>	V 00V/V 0V	-	3510	-	pF
Output Capacitance	Coss	$V_{DS}=20V, V_{GS}=0V,$	-	1050	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	60	-	pF
Switching Characteristics (Note 1)			<u>.</u>			
Turn-on Delay Time	t <sub>d(on)</sub>		-	10.5	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =20V, $I_{D}$ =20A $V_{GS}$ =10V, $R_{G}$ =1.6 $\Omega$	-	4	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	35	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	5	-	nS
Total Gate Charge	Qg	V 00VI 00A	-	60	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}=20V,I_{D}=20A,$	-	9.9	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V		9.5	-	nC
Drain-Source Diode Characteristics			•	•		
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =55A	-	-	1.2	V
Diode Forward Current	Is		-	-	150	Α
Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25^{\circ}C$ , $I_F = I_S$	-	24	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s$	-	68	-	nC

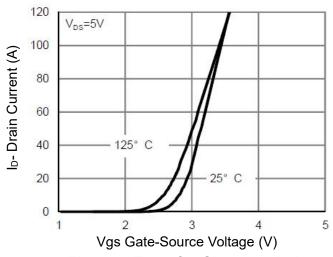
### Notes:

- 1. Defined by design.Not Subject to production test
- 2. EAS condition : Tj=25  $^{\circ}\!\!\mathrm{C}$  ,V\_DD=20V,VG=10V,L=0.5mH,Rg=25 $\!\Omega$
- 4. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of TJ(MAX)=175° C. The SOA curve provides a single pulse rating.

### **Typical Electrical and Thermal Characteristics**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

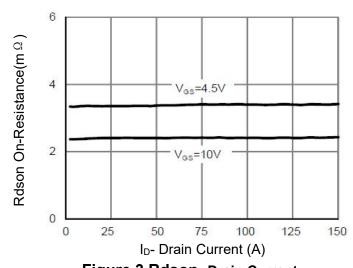


Figure 3 Rdson- Drain Current

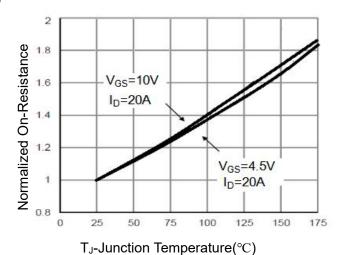


Figure 4 Rdson-JunctionTemperature

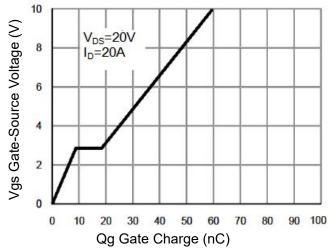


Figure 5 Gate Charge

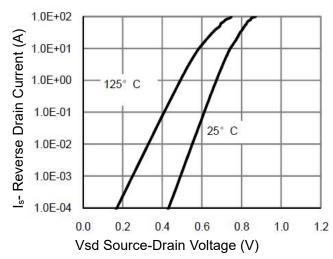


Figure 6 Source- Drain Diode Forward

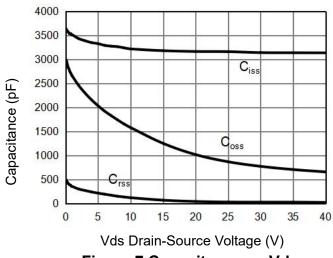


Figure 7 Capacitance vs Vds

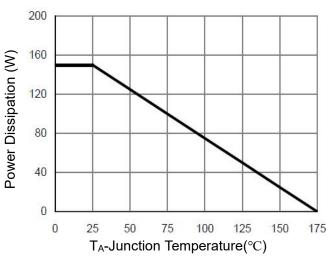


Figure 9 Power De-rating

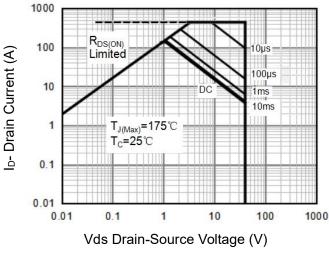


Figure 8 Safe Operation Area (Note 3)

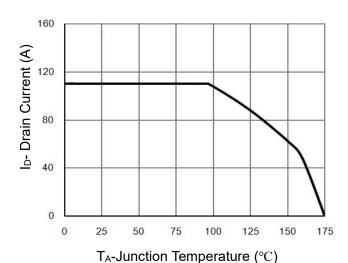


Figure 10 Current De-rating

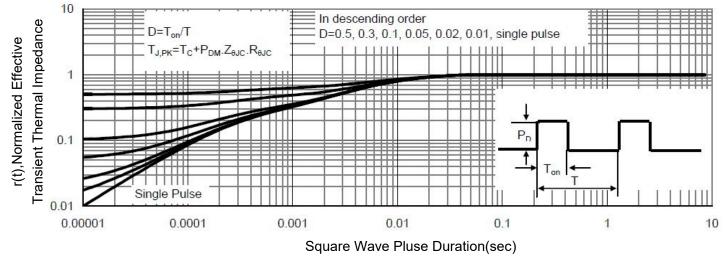
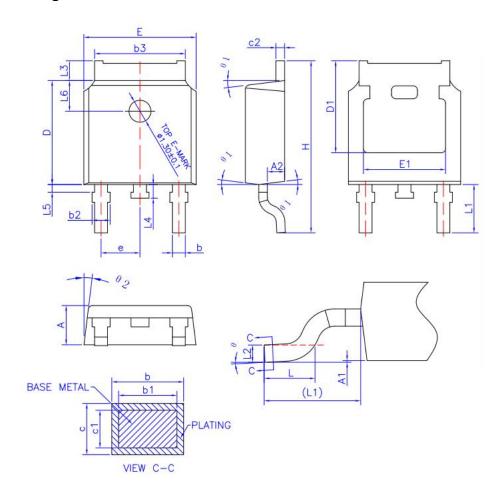


Figure 11 Normalized Maximum Transient Thermal Impedance

# **TO-252-2L Package Information**



7120			- 1
SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0		0.10
A2	0.90	1.01	1.10
b	0.72		0.85
b1	0.71	0.76	0.81
b2	0.72		0.90
b3	5.13	5.33	5.46
С	0.47		0.60
c1	0.46	0.51	0.56
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.25		
E	6.50	6.60	6.70
E1	4.70		
е	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF 0.508 BSC		
L2			
L3	0.90		1.25
L4	0.60	0.80	1.00
L5	0.15		0.75
L6	1.80 REF		
θ	0°		8°
θ1	5°	7°	9°
θ2	5°	7°	9°

# NCEAP40T11K

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